

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	871201	"324"/\$.ccls. and ((test or inspection) adj pad) and wafer or chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:05
L2	870	"324"/\$.ccls. and ((test or inspection) adj pad) and (wafer or chip or substrate or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:06
L3	128	"361"/\$.ccls. and ((test or inspection) adj pad) and (wafer or chip or substrate or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:06
L4	849	"257"/\$.ccls. and ((test or inspection) adj pad) and (wafer or chip or substrate or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:07
L5	409	"257"/\$.ccls. and ((test or inspection) adj pad) and (wafer or chip or substrate or board) and (bond\$4 adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:07
L6	311	"324"/\$.ccls. and ((test or inspection) adj pad) and (wafer or chip or substrate or board) and (bond\$4 adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:07
L7	48	"361"/\$.ccls. and ((test or inspection) adj pad) and (wafer or chip or substrate or board) and (bond\$4 adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/12/23 10:07